# Electronic Patent Application Fee Transmittal

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| **Application Number:** | 10680664 |
| **Filing Date:** | 07-Oct-2003 |
| **Title of Invention:** | Integrated circuit package bond pad having plurality of conductive members |
| **First Named Inventor:** | Yian-Liang Kuo |
| **Filer:** | David M. Odell/Bonnie Boyle |
| **Attorney Docket Number:** | 24061.43 (TSMC2002-0978) |

Filed as Large Entity

## Utility Filing Fees

| Description | Fee Code | Quantity | Amount | Sub-Total in USD($) |
|---|---|---|---|---|
| **Basic Filing:** | | | | |
| **Pages:** | | | | |
| **Claims:** | | | | |
| **Miscellaneous-Filing:** | | | | |
| **Petition:** | | | | |
| **Patent-Appeals-and-Interference:** | | | | |
| Notice of appeal | 1401 | 1 | 500 | 500 |
| Post-Allowance-and-Post-Issuance: | | | | |
| **Extension-of-Time:** | | | | |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD($) |
|---|---|---|---|---|
| **Miscellaneous:** | | | | |
| | | | **Total in USD ($)** | **500** |